

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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Layers	in μ	Material	Build-Up	Assembly			
Layer-1	35 μ	Copper		A1			
	60 μ	Prepreg					
	60 μ	Prepreg					
Layer-2	35 μ	Copper			B		
	610 μ	L-FR4					
Layer-3	35 μ	Copper				A2	
	60 μ	Prepreg					
	60 μ	Prepreg					
Layer-4	35 μ	Copper					A1
	610 μ	L-FR4					
Layer-5	35 μ	Copper		B			
	60 μ	Prepreg					
	60 μ	Prepreg					
Layer-99	35 μ	Copper			A2		

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